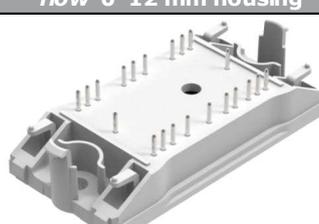
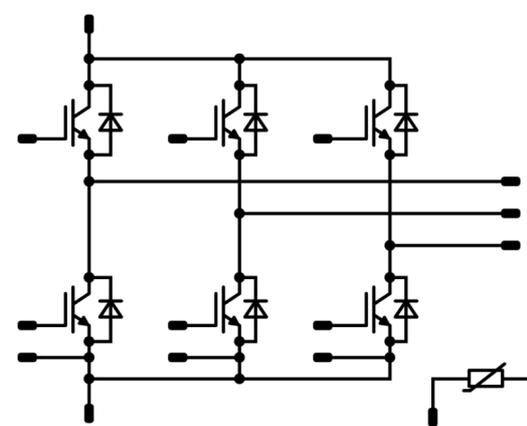




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<i>flow</i> PACK 0	1200 V / 15 A
<div style="border: 1px solid black; padding: 5px; margin-bottom: 5px;"> <p style="text-align: center; background-color: #ccc; margin: 0;">Features</p> <ul style="list-style-type: none"> IGBT M7 with low V_{CEsat} and improved EMC behavior Compact and low inductive design Built-in NTC </div> <div style="border: 1px solid black; padding: 5px; margin-bottom: 5px;"> <p style="text-align: center; background-color: #ccc; margin: 0;">Target applications</p> <ul style="list-style-type: none"> Industrial Drives </div> <div style="border: 1px solid black; padding: 5px;"> <p style="text-align: center; background-color: #ccc; margin: 0;">Types</p> <ul style="list-style-type: none"> 10-FZ126PA015M7-P868F78 </div>	<div style="border: 1px solid black; padding: 5px; margin-bottom: 5px;"> <p style="text-align: center; background-color: #ccc; margin: 0;"><i>flow</i> 0 12 mm housing</p>  </div> <div style="border: 1px solid black; padding: 5px;"> <p style="text-align: center; background-color: #ccc; margin: 0;">Schematic</p>  </div>

Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current	I_C		15	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	30	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	60	W
Gate-emitter voltage	V_{GES}		±20	V
Maximum junction temperature	T_{jmax}		175	°C



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Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Diode				
Peak repetitive reverse voltage	V_{RRM}		1200	V
Continuous (direct) forward current	I_F		15	A
Repetitive peak forward current	I_{FRM}	T_j limited by T_{jmax}	30	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	45	W
Maximum junction temperature	T_{jmax}		175	°C

Module Properties

Thermal Properties

Storage temperature	T_{stg}		-40...+125	°C
Operation temperature under switching condition	T_{jop}		-40...($T_{jmax} - 25$)	°C

Isolation Properties

Isolation voltage	V_{isol}	DC Test Voltage* $t_p = 2\text{ s}$	6000	V
		AC Voltage $t_p = 1\text{ min}$	2500	V
Creepage distance			min. 12,7	mm
Clearance			9,22	mm
Comparative Tracking Index	CTI		> 200	

*100 % tested in production



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Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
		V_{GS} [V]	V_{GE} [V]	V_{DS} [V]	I_D [A]	T_j [°C]	Min	Typ	Max	

Inverter Switch

Static

Parameter	Symbol	Conditions	V_{GS} [V]	V_{GE} [V]	V_{DS} [V]	I_D [A]	T_j [°C]	Min	Typ	Max	Unit
Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{GE} = V_{CE}$				0,0015	25	5,4	6	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15			15	25 125 150		1,70 1,95 2,01	1,95	V
Collector-emitter cut-off current	I_{CES}		0	1200			25			60	μA
Gate-emitter leakage current	I_{GES}		20	0			25			500	nA
Internal gate resistance	r_g								none		Ω
Input capacitance	C_{ies}								2900		pF
Output capacitance	C_{oes}		0	10		25			120		
Reverse transfer capacitance	C_{res}								34		
Gate charge	Q_g		15	600	15	25			110		nC

Thermal

Parameter	Symbol	Conditions	V_{GS} [V]	V_{GE} [V]	V_{DS} [V]	I_D [A]	T_j [°C]	Min	Typ	Max	Unit
Thermal resistance junction to sink	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)							1,60		K/W

Dynamic

Parameter	Symbol	Conditions	V_{GS} [V]	V_{GE} [V]	V_{DS} [V]	I_D [A]	T_j [°C]	Min	Typ	Max	Unit
Turn-on delay time	$t_{d(on)}$	$R_{goff} = 32$ Ω $R_{gon} = 32$ Ω	±15	600	15	25	25		176		ns
Rise time	t_r							150	174		
Turn-off delay time	$t_{d(off)}$							25	43		
Fall time	t_f							150	48		
Turn-on energy (per pulse)	E_{on}							25	191		
Turn-off energy (per pulse)	E_{off}							150	218		
			119						1,548		mWs
			127						2,008		
			25						0,925		
			150						1,322		



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Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
		V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V]	I_C [A] I_D [A]	I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	

Inverter Diode

Static

Forward voltage	V_F				15	25 125 150		1,63 1,74 1,73	2,1	V
Reverse leakage current	I_R			1200		25			30	μA

Thermal

Thermal resistance junction to sink	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						2,11		K/W
-------------------------------------	---------------	---------------------------------------	--	--	--	--	--	------	--	-----

Dynamic

Peak recovery current	I_{RRM}					25 150		11 12		A
Reverse recovery time	t_{rr}					25 150		265 423		ns
Recovered charge	Q_r	$di/dt = 293$ A/μs $di/dt = 244$ A/μs	±15	600	15	25 150		1,549 2,592		μC
Reverse recovered energy	E_{rec}					25 150		0,488 0,938		mWs
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$					25 150		92 52		A/μs

Thermistor

Rated resistance	R					25		22		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	$R_{100} = 1484$ Ω				100	-5		5	%
Power dissipation	P					25		5		mW
Power dissipation constant						25		1,5		mW/K
B-value	$B_{(25/50)}$	Tol. ±1 %				25		3962		K
B-value	$B_{(25/100)}$	Tol. ±1 %				25		4000		K
Vincotech NTC Reference									I	

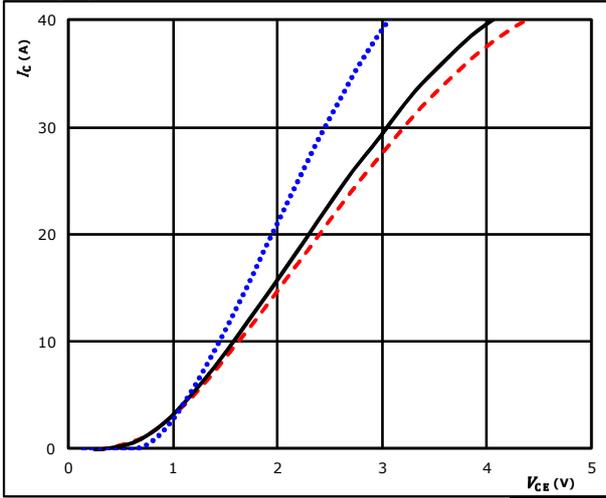


Inverter Switch Characteristics

figure 1. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

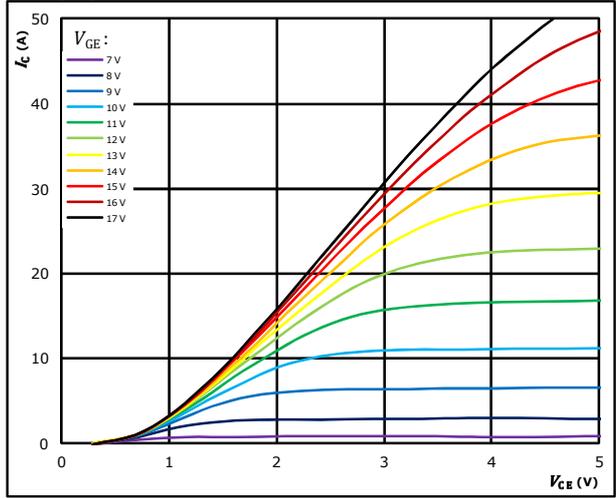


$t_p = 250 \mu s$ $T_j: 25 \text{ }^\circ C$
 $V_{GE} = 15 \text{ V}$ $T_j: 125 \text{ }^\circ C$ ———
 $T_j: 150 \text{ }^\circ C$ - - - - -

figure 2. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

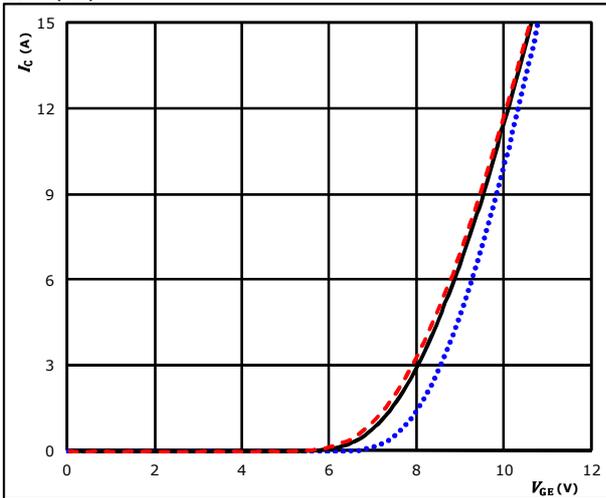


$t_p = 250 \mu s$
 $T_j = 150 \text{ }^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. IGBT

Typical transfer characteristics

$$I_C = f(V_{GE})$$

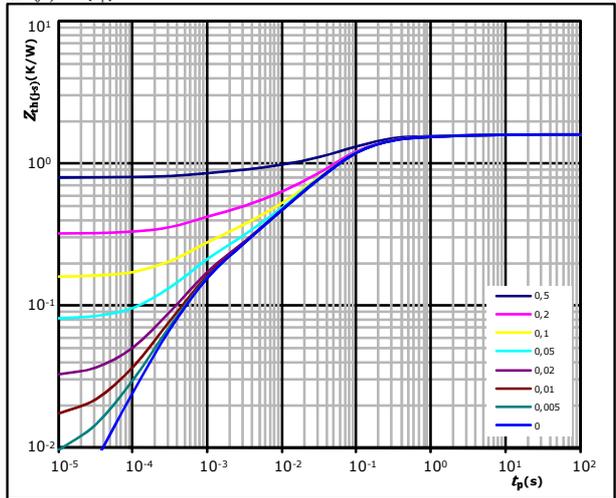


$t_p = 100 \mu s$ $T_j: 25 \text{ }^\circ C$
 $V_{CE} = 10 \text{ V}$ $T_j: 125 \text{ }^\circ C$ ———
 $T_j: 150 \text{ }^\circ C$ - - - - -

figure 4. IGBT

Transient thermal impedance as function of pulse duration

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 1,60 \text{ K/W}$
 IGBT thermal model values

R (K/W)	τ (s)
4,90E-02	4,40E+00
1,40E-01	5,34E-01
8,04E-01	8,02E-02
2,98E-01	2,57E-02
1,69E-01	5,09E-03
1,35E-01	6,41E-04

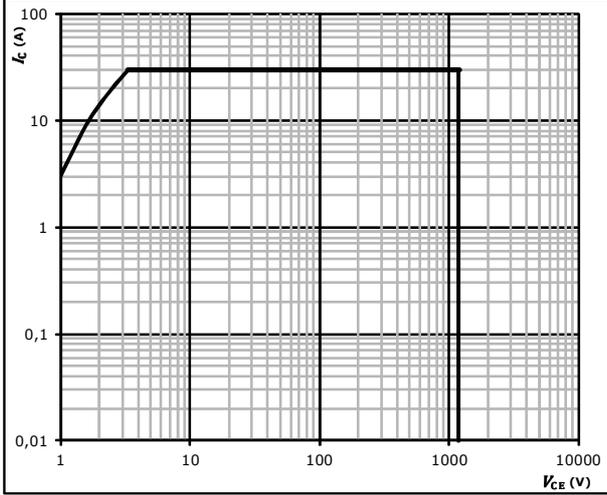


Inverter Switch Characteristics

figure 5. IGBT

Safe operating area

$I_C = f(V_{CE})$



- $D =$ single pulse
- $T_s =$ 80 °C
- $V_{GE} =$ ±15 V
- $T_j =$ T_{jmax}

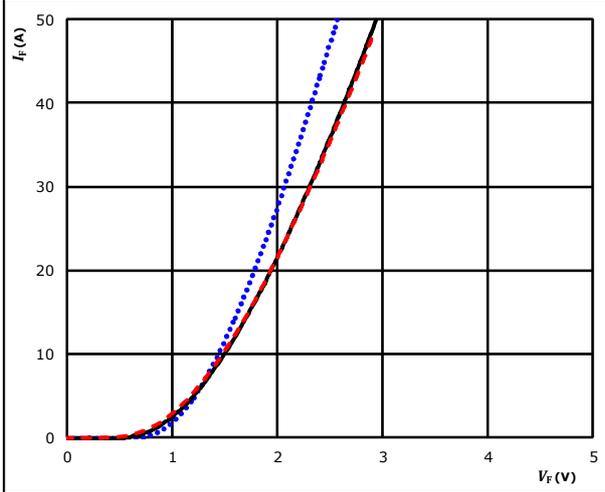


Inverter Diode Characteristics

figure 1. FWD

Typical forward characteristics

$$I_F = f(V_F)$$

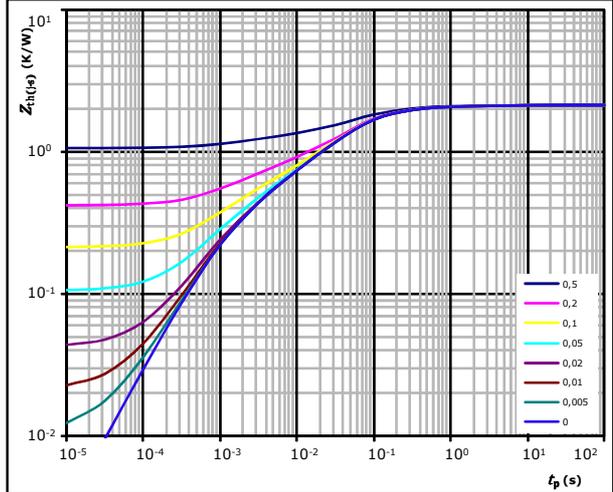


$t_p = 250 \mu s$
 T_j : 25 °C (blue dotted line)
 125 °C (black solid line)
 150 °C (red dashed line)

figure 2. FWD

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 2,11 \text{ K/W}$
 FWD thermal model values

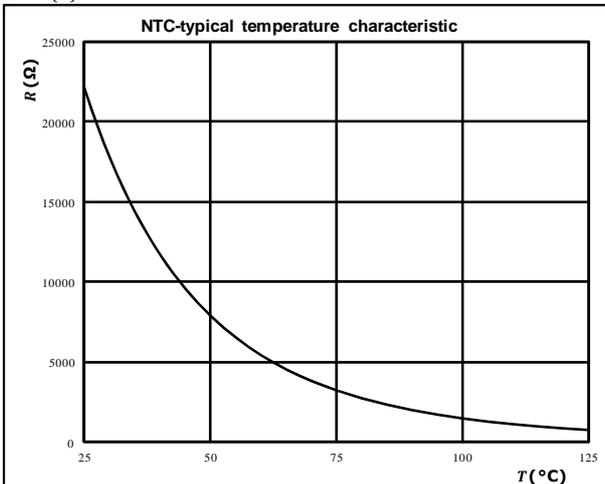
R (K/W)	τ (s)
8,99E-02	2,33E+00
4,04E-01	1,91E-01
1,05E+00	4,49E-02
3,39E-01	6,08E-03
2,29E-01	1,02E-03

Thermistor Characteristics

figure 1. Thermistor

Typical NTC characteristic as a function of temperature

$$R = f(T)$$

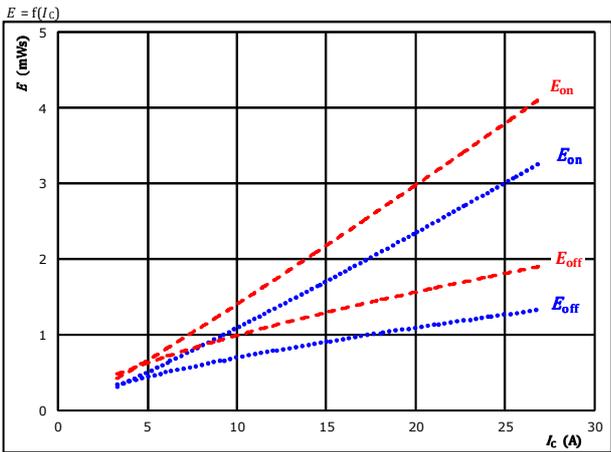




Inverter Switching Characteristics

figure 1. IGBT

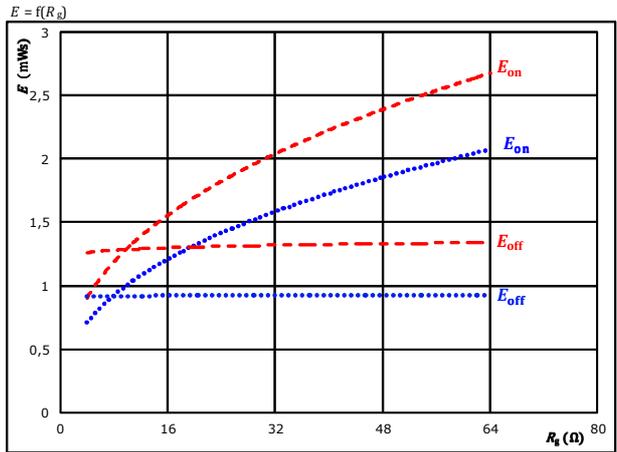
Typical switching energy losses as a function of collector current



With an inductive load at
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 32$ Ω
 $R_{goff} = 32$ Ω
 $T_j: 25$ $^{\circ}C$ (Blue Dotted)
 150 $^{\circ}C$ (Red Dashed)

figure 2. IGBT

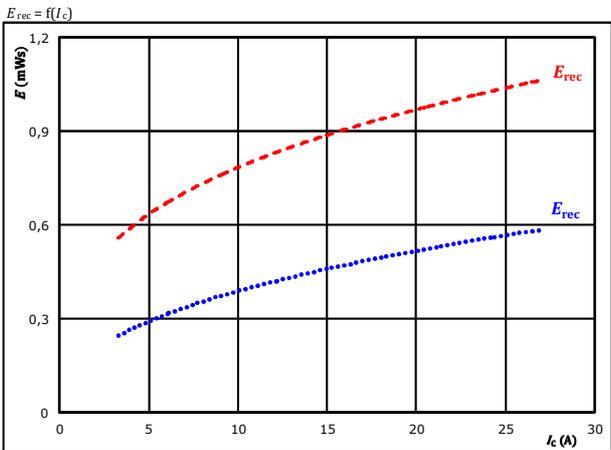
Typical switching energy losses as a function of gate resistor



With an inductive load at
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_C = 15$ A
 $T_j: 25$ $^{\circ}C$ (Blue Dotted)
 150 $^{\circ}C$ (Red Dashed)

figure 3. FWD

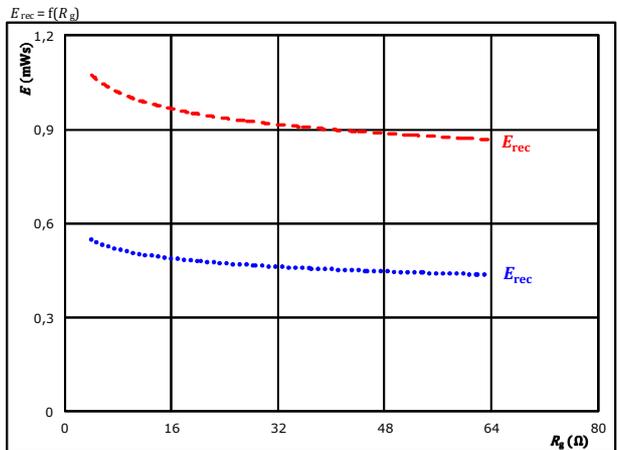
Typical reverse recovered energy loss as a function of collector current



With an inductive load at
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 32$ Ω
 $T_j: 25$ $^{\circ}C$ (Blue Dotted)
 150 $^{\circ}C$ (Red Dashed)

figure 4. FWD

Typical reverse recovered energy loss as a function of gate resistor



With an inductive load at
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_C = 15$ A
 $T_j: 25$ $^{\circ}C$ (Blue Dotted)
 150 $^{\circ}C$ (Red Dashed)

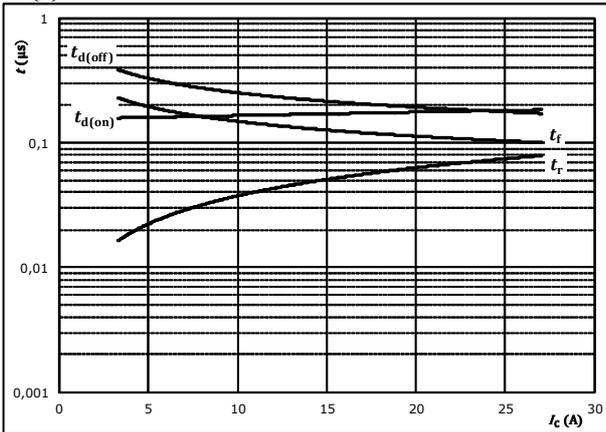


Inverter Switching Characteristics

figure 5. IGBT

Typical switching times as a function of collector current

$$t = f(I_C)$$



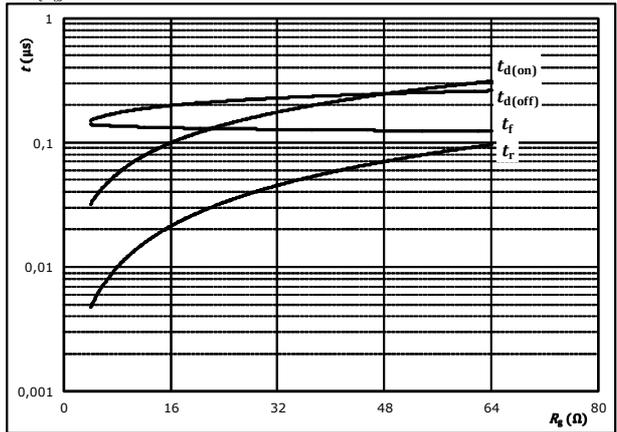
With an inductive load at

$T_j =$	150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	32	Ω
$R_{goff} =$	32	Ω

figure 6. IGBT

Typical switching times as a function of gate resistor

$$t = f(R_g)$$



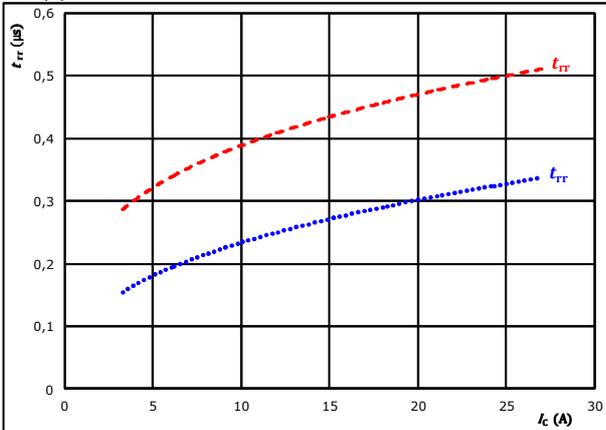
With an inductive load at

$T_j =$	150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$I_C =$	15	A

figure 7. FWD

Typical reverse recovery time as a function of collector current

$$t_{rr} = f(I_C)$$

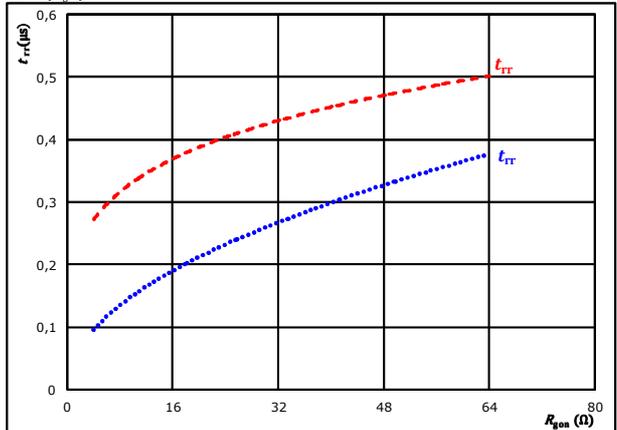


At	$V_{CE} =$	600	V	$T_j =$	25 °C
	$V_{GE} =$	±15	V		150 °C	-----
	$R_{gon} =$	32	Ω			

figure 8. FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor

$$t_{rr} = f(R_{gon})$$



At	$V_{CE} =$	600	V	$T_j =$	25 °C
	$V_{GE} =$	±15	V		150 °C	-----
	$I_C =$	15	A			

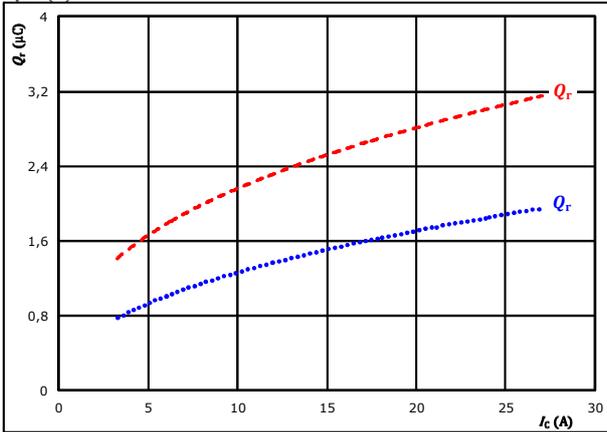


Inverter Switching Characteristics

figure 9. FWD

Typical recovered charge as a function of collector current

$$Q_r = f(I_c)$$

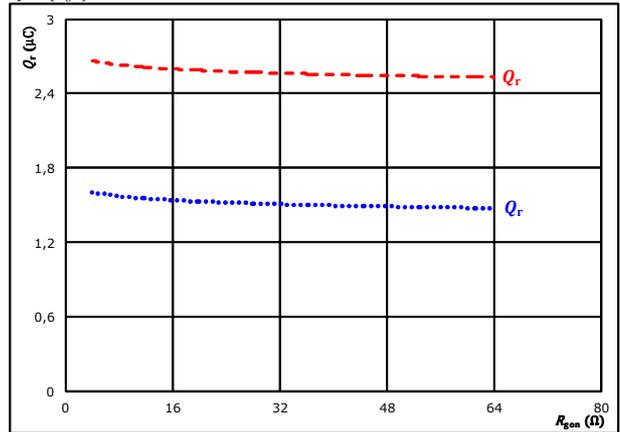


At $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{ggn} = 32$ Ω
 $T_j: 25$ °C (blue dotted line)
 150 °C (red dashed line)

figure 10. FWD

Typical recovered charge as a function of IGBT turn on gate resistor

$$Q_r = f(R_{ggn})$$

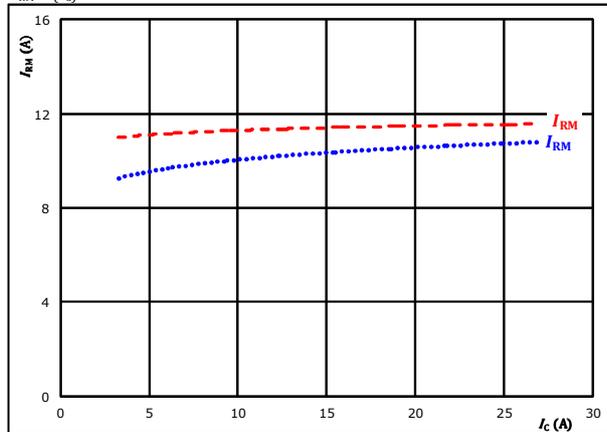


At $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_c = 15$ A
 $T_j: 25$ °C (blue dotted line)
 150 °C (red dashed line)

figure 11. FWD

Typical peak reverse recovery current as a function of collector current

$$I_{RM} = f(I_c)$$

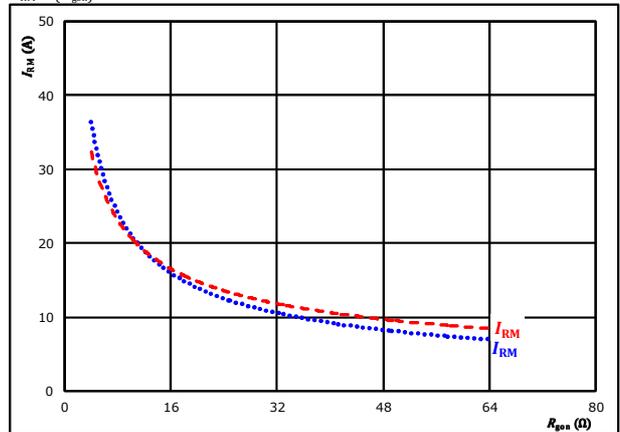


At $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{ggn} = 32$ Ω
 $T_j: 25$ °C (blue dotted line)
 150 °C (red dashed line)

figure 12. FWD

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RM} = f(R_{ggn})$$



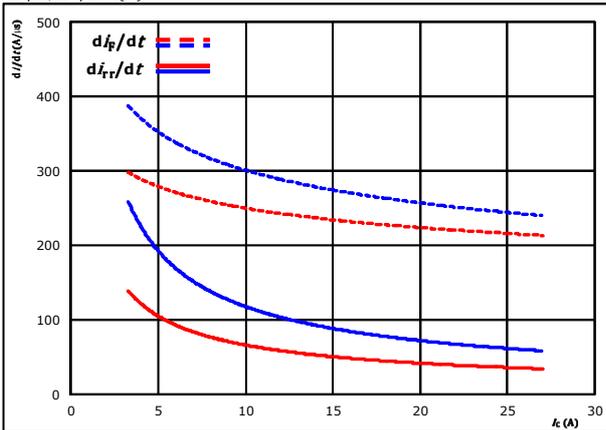
At $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_c = 15$ A
 $T_j: 25$ °C (blue dotted line)
 150 °C (red dashed line)



Inverter Switching Characteristics

figure 13. FWD

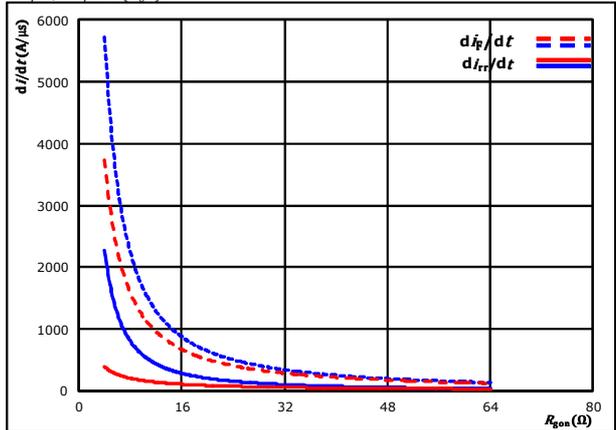
Typical rate of fall of forward and reverse recovery current as a function of collector current
 $di_f/dt, di_{rr}/dt = f(I_c)$



At $V_{CE} = 600$ V $T_j = 25$ °C (.....)
 $V_{GE} = \pm 15$ V $T_j = 150$ °C (----)
 $R_{g(on)} = 32$ Ω

figure 14. FWD

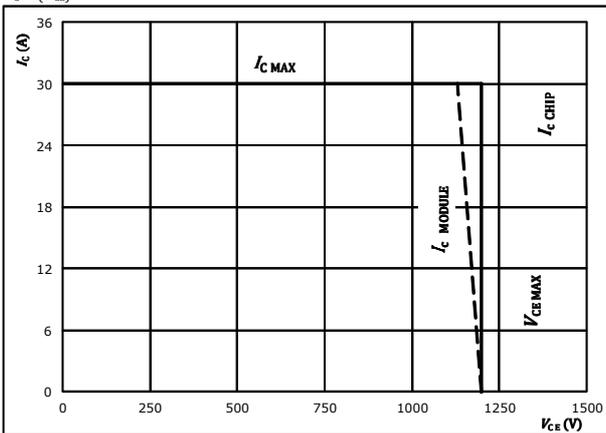
Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor
 $di_f/dt, di_{rr}/dt = f(R_{g(on)})$



At $V_{CE} = 600$ V $T_j = 25$ °C (.....)
 $V_{GE} = \pm 15$ V $T_j = 150$ °C (----)
 $I_c = 15$ A

figure 15. IGBT

Reverse bias safe operating area
 $I_c = f(V_{CE})$



At $T_j = 175$ °C
 $R_{g(on)} = 32$ Ω
 $R_{g(off)} = 32$ Ω



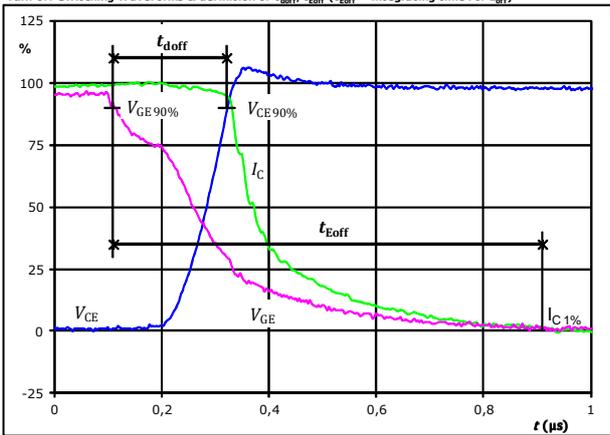
Inverter Switching Definitions

General conditions

T_j	=	150 °C
R_{gon}	=	32 Ω
R_{goff}	=	32 Ω

figure 1. IGBT

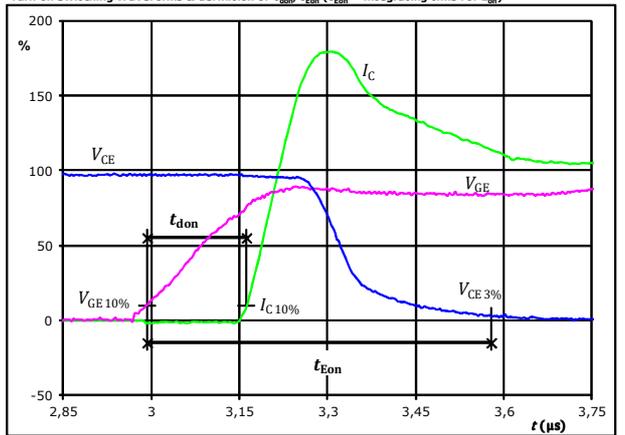
Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff} (t_{Eoff} = integrating time for E_{off})



$V_{CE}(0\%) =$	-15	V
$V_{GE}(100\%) =$	15	V
$V_C(100\%) =$	600	V
$I_C(100\%) =$	15	A
$t_{doff} =$	0,218	μs
$t_{Eoff} =$	0,800	μs

figure 2. IGBT

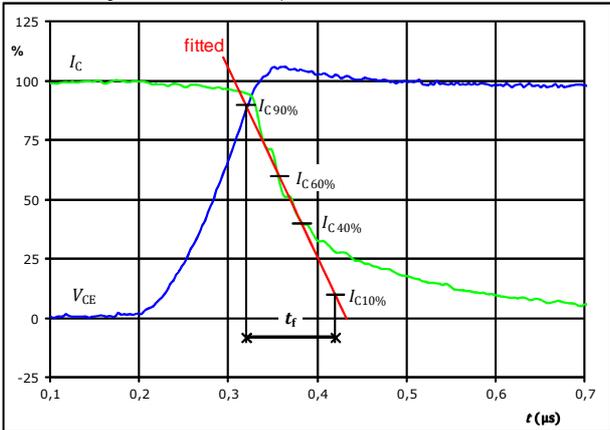
Turn-on Switching Waveforms & definition of t_{don} , t_{Eon} (t_{Eon} = integrating time for E_{on})



$V_{CE}(0\%) =$	-15	V
$V_{GE}(100\%) =$	15	V
$V_C(100\%) =$	600	V
$I_C(100\%) =$	15	A
$t_{don} =$	0,174	μs
$t_{Eon} =$	0,586	μs

figure 3. IGBT

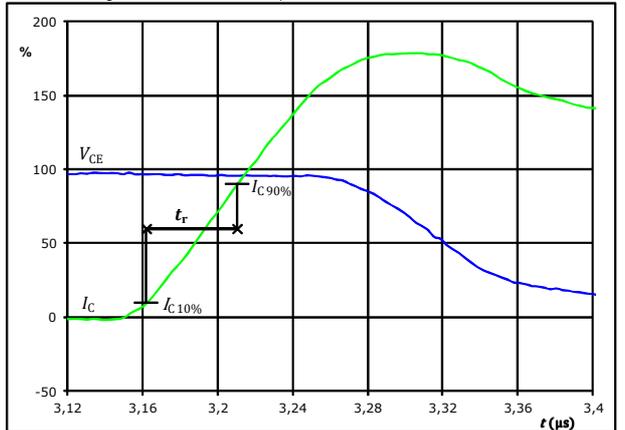
Turn-off Switching Waveforms & definition of t_f



$V_C(100\%) =$	600	V
$I_C(100\%) =$	15	A
$t_f =$	0,127	μs

figure 4. IGBT

Turn-on Switching Waveforms & definition of t_r



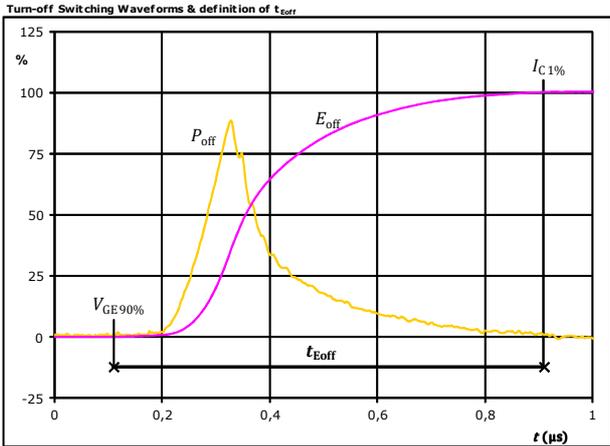
$V_C(100\%) =$	600	V
$I_C(100\%) =$	15	A
$t_r =$	0,048	μs



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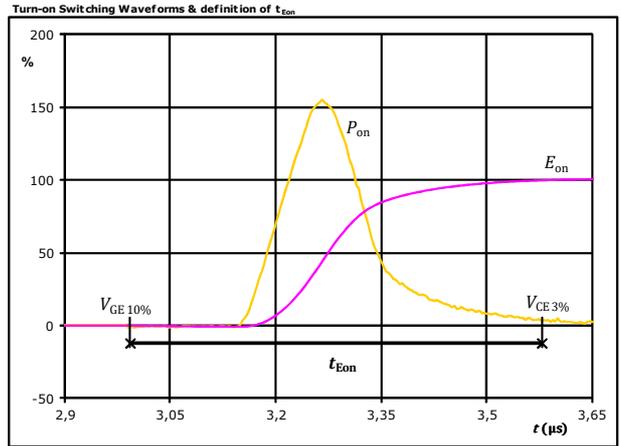
Inverter Switching Characteristics

figure 5. IGBT



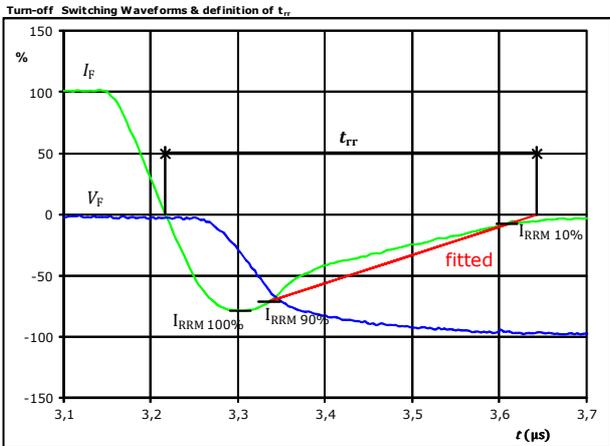
$P_{off}(100\%) = 9,24$ kW
 $E_{off}(100\%) = 1,32$ mJ
 $t_{Eoff} = 0,80$ μs

figure 6. IGBT



$P_{on}(100\%) = 9,24$ kW
 $E_{on}(100\%) = 2,01$ mJ
 $t_{Eon} = 0,59$ μs

figure 7. FWD



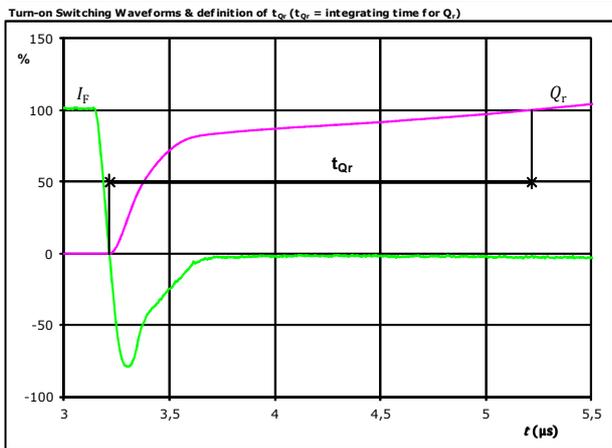
$V_F(100\%) = 600$ V
 $I_F(100\%) = 15$ A
 $I_{RRM}(100\%) = -12$ A
 $t_{rr} = 0,423$ μs



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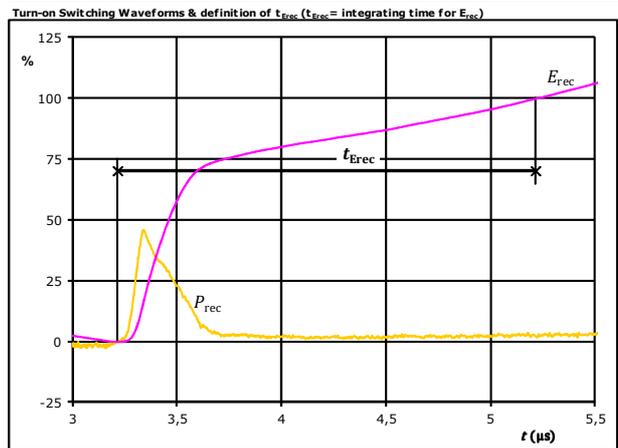
Inverter Switching Characteristics

figure 8. FWD



I_F (100%) =	15	A
Q_r (100%) =	2,59	μC
t_{Qr} =	2,00	μs

figure 9. FWD



P_{rec} (100%) =	9,24	kW
E_{rec} (100%) =	0,94	mJ
t_{Erec} =	2,00	μs



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Ordering Code & Marking																																
Version			Ordering Code																													
without thermal paste 12 mm housing with solder pins			10-FZ126PA015M7-P868F78																													
<table border="1"> <thead> <tr> <th rowspan="2">Text</th> <th colspan="2">Name</th> <th>Date code</th> <th>UL & VIN</th> <th>Lot</th> <th>Serial</th> </tr> <tr> <th>Type&Ver</th> <th>Lot number</th> <th>Serial</th> <th>Date code</th> <td></td> <td></td> </tr> </thead> <tbody> <tr> <td rowspan="2"> NN-NNNNNNNNNNNNNN TTTTWTW WYYY UL VIN LLLLL SSSS </td> <td colspan="2">NN-NNNNNNNNNNNNNN-TTTTWTW</td> <td>WYYY</td> <td>UL VIN</td> <td>LLLLL</td> <td>SSSS</td> </tr> <tr> <td>TTTTTWTW</td> <td>LLLLL</td> <td>SSSS</td> <td>WYYY</td> <td></td> <td></td> </tr> </tbody> </table>							Text	Name		Date code	UL & VIN	Lot	Serial	Type&Ver	Lot number	Serial	Date code			NN-NNNNNNNNNNNNNN TTTTWTW WYYY UL VIN LLLLL SSSS	NN-NNNNNNNNNNNNNN-TTTTWTW		WYYY	UL VIN	LLLLL	SSSS	TTTTTWTW	LLLLL	SSSS	WYYY		
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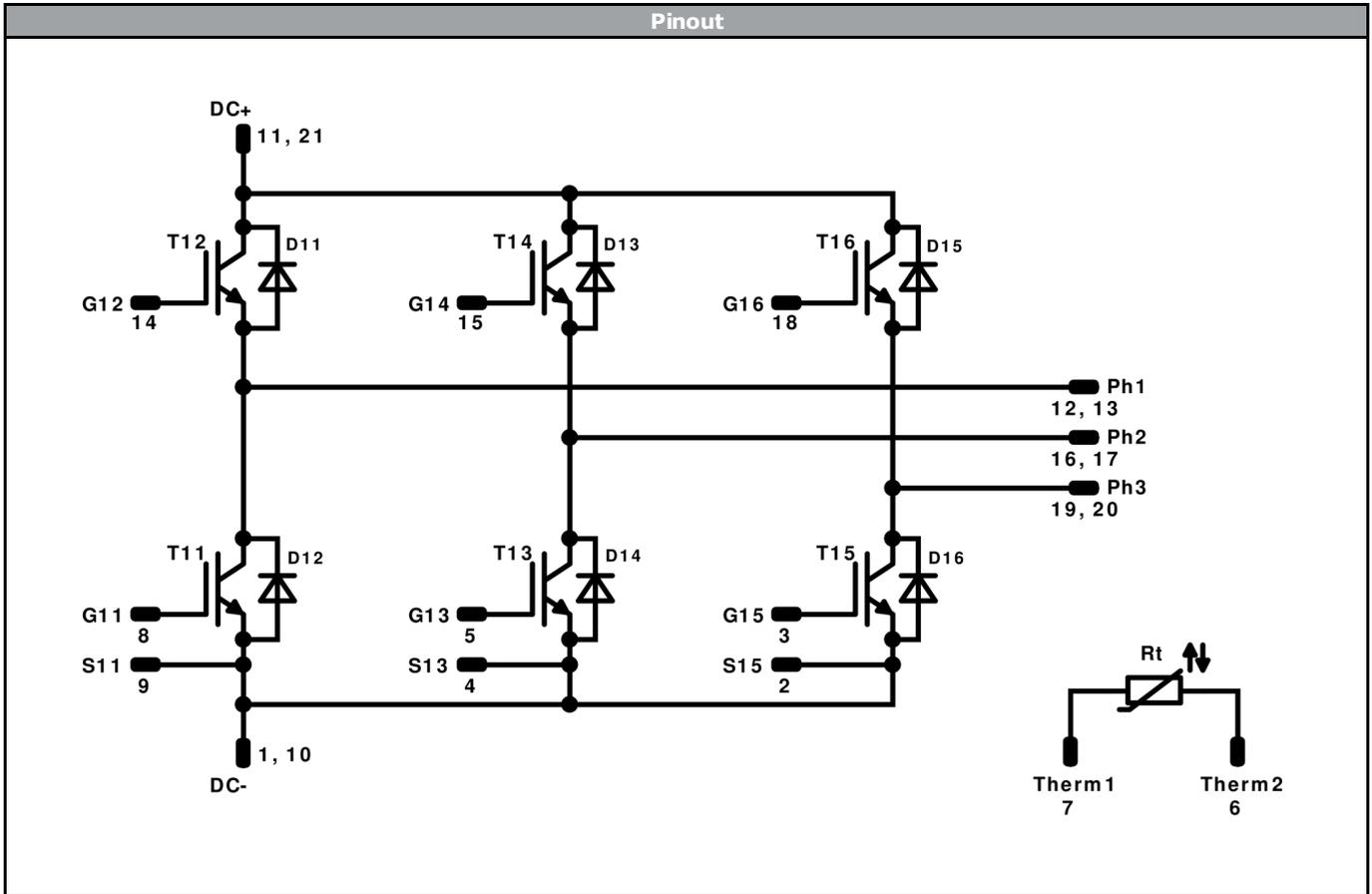
Pin table			
Pin	X	Y	Function
1	33,3	0	DC-
2	30,7	0	S15
3	27,9	0	G15
4	23,85	0	S13
5	21,05	0	G13
6	15,95	0	Therm2
7	9,6	0	Therm1
8	5,4	0	G11
9	2,6	0	S11
10	0	0	DC-
11	0	11,15	DC+
12	0	22,3	Ph1
13	2,6	22,3	Ph1
14	5,5	22,3	G12
15	13,1	22,3	G14
16	15,9	22,3	Ph2
17	19,4	22,3	Ph2
18	27,7	22,3	G16
19	30,7	22,3	Ph3
20	33,3	22,3	Ph3
21	33,3	11,15	DC+

$\phi 1\pm 0.05$
 16.3 ± 0.5
 11.15
 16.65

Tolerance of pinpositions: $\pm 0.5\text{mm}$ at the end of pins
Dimension of coordinate axis is only offset without tolerance



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Identification					
ID	Component	Voltage	Current	Function	Comment
T11 - T16	IGBT	1200 V	15 A	Inverter Switch	
D11 - D16	FWD	1200 V	15 A	Inverter Diode	
Rt	NTC			Thermistor	



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Packaging instruction			
Standard packaging quantity (SPQ) 135	>SPQ	Standard	<SPQ Sample

Handling instruction
Handling instructions for <i>flow 0</i> packages see vincotech.com website.

Package data
Package data for <i>flow 0</i> packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website. 

Document No.:	Date:	Modification:	Pages
10-FZ126PA015M7-P868F78-D1-14	24 Nov. 2017		

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